PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5666486

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DAVID CAO	08/07/2019
CHENG-CHIEH CHAO	07/08/2019
ZHEBO CHEN	07/09/2019
LEI CHENG	07/06/2019
NIALL DONNELLY	07/03/2019
WESTON HERMANN	07/01/2019
TIMOTHY HOLME	07/01/2019
TOMMY HUANG	07/01/2019
YANG LI	07/01/2019
HARSH MAHESHWARI	07/02/2019
KIAN KERMAN	07/09/2019

RECEIVING PARTY DATA

Name:	QUANTUMSCAPE CORPORATION
Street Address:	1730 TECHNOLOGY DRIVE
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95110

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16343361

CORRESPONDENCE DATA

Fax Number: (650)843-8777

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 6508433288
Email: steven.goldstein@squirepb.com
Correspondent Name: SQUIRE PATTON BOGGS [US] LLP
Address Line 1: 1801 PAGE MILL ROAD, SUITE 110
Address Line 4: PALO ALTO, CALIFORNIA 94304

ATTORNEY DOCKET NUMBER:	114826.00351
NAME OF SUBMITTER:	TODD OSTOMEL
SIGNATURE:	/ToddOstomelReg63426/
DATE SIGNED:	08/13/2019

Total Attachments: 11

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ASSIGNMENT

WHEREAS, I, **David CAO**, ASSIGNOR, citizen of the United States, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

and WHEREAS, **QuantumScape Corporation**, a corporation organized and existing under the laws of the state of Delaware, and having an office for the transaction of business at 1730 Technology Drive, San Jose, California, 95110, herein referred to as "ASSIGNEE", is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 8/7/2019 ______________________ L.S.
David CAO

Date 8/7/19 ______________________ Virgil Xu
Witness (sign and print name)

Date 8/7/19 ______________________ Doo Haro.
Witness (sign and print name)

Page 1 of 1

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108.831

ASSIGNMENT

WHEREAS, I, **Cheng-Chieh CHAO**, ASSIGNOR, citizen of Taiwan, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

and WHEREAS, **QuantumScape Corporation,** a corporation organized and existing under the laws of the state of Delaware, and having an office for the transaction of business at 1730 Technology Drive, San Jose, California, 95110, herein referred to as "ASSIGNEE", is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 7/8/2019 ______________________ L.S.
Cheng-Chieh CHAO

Date 7/8/2019 Yang Li Yang Li
Witness (sign and print name)

Date 7/8/2019 Zhenfeng Yu
Witness (sign and print name)

ASSIGNMENT

WHEREAS, I, **Zhebo CHEN**, ASSIGNOR, citizen of the United States, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

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NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

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AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 7/9/19 ______________________ L.S.
Zhebo CHEN

Date 7/9/2019 ______________________ DAVID CAO
Witness (sign and print name)

Date 7/9/2019 ______________________ Ka Ki Yip
Witness (sign and print name)

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ASSIGNMENT

WHEREAS, I, Lei CHENG, ASSIGNOR, citizen of the People's Republic of China, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

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NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

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AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 07/06/2019 ______________________ L.S.
Lei CHENG

Date 07/06/2019 QIAN YU.
Witness (sign and print name)

Date ______________ ______________________
Witness (sign and print name)

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108.831

ASSIGNMENT

WHEREAS, I, **Niall DONNELLY**, ASSIGNOR, citizen of the United States, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

and WHEREAS, **QuantumScape Corporation**, a corporation organized and existing under the laws of the state of Delaware, and having an office for the transaction of business at 1730 Technology Drive, San Jose, California, 95110, herein referred to as "ASSIGNEE", is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 7/3/19 Niall Donnelly L.S.
Niall DONNELLY

Date 7/3/19 Noushin Emadi
Witness (sign and print name)

Date 7/3/19 Jellian McDonell
Witness (sign and print name)

ASSIGNMENT

WHEREAS, I, **Weston HERMANN**, ASSIGNOR, citizen of the United States, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

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NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

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AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 7/1/19 ______________________ L.S.
Weston HERMANN

Date 7/1/2019 Marie A Mayer
Witness (sign and print name)

Date 7/1/2019 ______________________
Witness (sign and print name)

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ASSIGNMENT

WHEREAS, I, **Timothy HOLME**, ASSIGNOR, citizen of the United States, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

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NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

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AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 7-1-19 Tim Holme L.S.
Timothy HOLME

Date 7-1-19 Greg Gruebernike
Witness (sign and print name)

Date 7-1-19 Brian Ta
Witness (sign and print name)

114826.00351
108.831

ASSIGNMENT

WHEREAS, I, **Tommy HUANG**, ASSIGNOR, citizen of the United States, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

and WHEREAS, **QuantumScape Corporation**, a corporation organized and existing under the laws of the state of Delaware, and having an office for the transaction of business at 1730 Technology Drive, San Jose, California, 95110, herein referred to as "ASSIGNEE", is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

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AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 7/1/19 L.S.
Tommy HUANG

Date 7/1/19 G Lee Gloria Lee
Witness (sign and print name)

Date 7/1/19. Don Hao 7.1.19 Don HAO.
Witness (sign and print name)

ASSIGNMENT

WHEREAS, I, **Kian KERMAN**, ASSIGNOR, citizen of the United States, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826 00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

and WHEREAS, **QuantumScape Corporation**, a corporation organized and existing under the laws of the state of Delaware, and having an office for the transaction of business at 1730 Technology Drive, San Jose, California, 95110, herein referred to as "ASSIGNEE", is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 7/9/2019 ______________________ L.S.
Kian KERMAN

Date 7/9/2019 DAVID CAO
Witness (sign and print name)

Date 7/9/2019 Ka Ki Yip
Witness (sign and print name)

114826.00351
108.831

ASSIGNMENT

WHEREAS, I, **Yang LI**, ASSIGNOR, citizen of the People's Republic of China, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

and WHEREAS, **QuantumScape Corporation**, a corporation organized and existing under the laws of the state of Delaware, and having an office for the transaction of business at 1730 Technology Drive, San Jose, California, 95110, herein referred to as "ASSIGNEE", is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 7/1/2019 Yang Li L.S.
Yang LI

Date 7/1/2019 Donghyeok Han. DONGHYEOK HAN.
Witness (sign and print name)

Date 7/1/2019 Martin E. Holzwarth Jr
Witness (sign and print name)

114826.00351
108.831

ASSIGNMENT

WHEREAS, I, **Harsh MAHESHWARI**, ASSIGNOR, citizen of India, with a mailing address at c/o QuantumScape Corporation, 1730 Technology Drive, San Jose, California, 95110, in relation to the invention for which an application for patent has been filed on **April 18, 2019**, as U.S. Application No. **16/343,361** (Docket No. 114826.00351), entitled

LITHIUM-STUFFED GARNET ELECTROLYTES WITH A REDUCED SURFACE DEFECT DENSITY AND METHODS OF MAKING AND USING THE SAME

and WHEREAS, **QuantumScape Corporation**, a corporation organized and existing under the laws of the state of Delaware, and having an office for the transaction of business at 1730 Technology Drive, San Jose, California, 95110, herein referred to as "ASSIGNEE", is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said application and all applications claiming priority thereto and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signature.

Date 07/02/2019 — HMaheshwari L.S.
Harsh MAHESHWARI

Date 07/02/2019 — VRAJESH PADHIAR
Witness (sign and print name)

Date 07/02/19 — DEEPAK VIDHANI
Witness (sign and print name)